Filename: BILLOFMATERIALS_bom.xls
Date: 08/27/2012

PMP7182_RevB BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C101	3.3nF	Capacitor, Ceramic,	0603	STD	STD
1	C102	680pF	Capacitor, Ceramic,	0603	STD	STD
1	C103	DNP	Capacitor, Ceramic,	0603	STD	STD
1	C104	47p	Capacitor, Ceramic,	0603	STD	STD
1	C105	330pF	Capacitor, Ceramic,	0603	STD	STD
1	C106	1000pF	Capacitor, Ceramic,	0603	STD	STD
1	C107	1500pF	Capacitor, Ceramic Disk, 220V		ECKANAxxxMB	Panasonic
1	C108	33uF	Capacitor, Aluminum, SM, vvV,	5 x 5.8 mm	EEEFK1E220R	Panasonic
1	C109	0.1uF	Capacitor, Ceramic,	0603	STD	STD
3	C110 C114 C120	DNP	Capacitor, Ceramic Chip, 16V, ±10%	1206	STD	STD
1	C111	330uF	Capacitor, Aluminum, SMT, 6.3V, [temp], [tol]	7343(D)	6TPE330ML	Sanyo
1	C112	22uF	Capacitor, Ceramic Chip, 6.3V, ±10%	1210	Std	STD
1	C113	100pF	Capacitor, Ceramic, 630V, C0G, 10%	1206		TDK
4	C115-116 C121-122	22uF	Capacitor, Ceramic Chip, 25V, ±10%	1210	Std	STD
2	C117 C119	0.033uF	Capacitor, Leaded, 305 VAC, ±yy%	0.157 x 0.512	B32922C3 xxx	Epcos
1	C118	10uF	Capacitor, Electrolytic 20±%	12.5x20 mm	EKXG401ELL100N	Nippon Che
1	C200	2.2uF	Capacitor, Ceramic Chip, xxV, ±10%	0805	STD	STD
1	C201	4.7nF	Capacitor, Ceramic,	0603	STD	STD
3	D101 D105 D108	15V	Diode, Zener, xx-V, yy-mA, zz-mW, q%	SOT23	MMBZ5245BLT1G	
1	D102	BAS19	Diode, Switching	SOT23	BAS19	Zetex
1	D103	MBRA140A	Diode, Rectifier, xx-mA, yy-V	SMA	STD	STD
1	D104	US1J	Diode, Schottky, xx-A, xx-V	SMB	STD	STD
1	D106	RH04	Bridge Rectifier, xxxV, 0.5A, Glass Passivated, Fast R	MiniDIP	RH06-T	Diodes
2	D107 D109	MURA120	Diode, Rectifier, xx-mA, yy-V	SMA	STD	STD
1	F101	0.5A	Fuse, TR5 Series			Wickmann
3	J101-103	TBD	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25		OST
1	L101	39mH	Inductor, Coupled ±30%	7.5x15 mm	744821039	WE

1	Q101	STP16N65M5	MOSFET, N-ch, xx-V, yy-mA, zz-milliOhms	TO220	STP16N65M5	Vishay
1	Q102	BSP135	MOSFET, Nch, 600V, 0.4 A, 8.5 Ohm	SOT-223	STN1HNK60	ST
1	R101	6.04k	Resistor, Chip, 1/16W, 0.1%	0603	STD	STD
2	R102 R108	2k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R103	3.74k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R104	1.8	Resistor, Chip, 1/16W, x%	0805	Std	Std
1	R105	1k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R106	10k	Resistor, Chip, 1/16W, 0.1%	0603	STD	STD
1	R107	DNP	Resistor, Chip, 1/16W, x%	0603	Std	Std
4	R109-110 R118 R120	0	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R111	15k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R112	49.9	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R113	3.4M	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R114	10	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R115	DNP	Resistor, Metal Film, 1/4 watt, ± 5%	2512	Std	STD
1	R116	100k	Resistor, Metal Film, 1/4 watt, ± 5%	2512	Std	STD
1	R117	10k	Resistor, Metal Film, 1/4 watt, ± 5%	1206	Std	Std
1	R119	100	Resistor, Metal Film, 1/4 watt, ± 5%	1206	Std	Std
1	T1	2.2 mH	Transformer, ±10%	0.665 x 0.740	750811831	
7	TP101 TP103-104 TP106 TP109-110 TP112	TBD	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch		Keystone
3	TP105 TP107 TP111	TBD	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch		Keystone
1	TP108	TBD	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100	5000	Keystone
1	U101	TLV431B	IC, Low-Voltage Adjustable Shunt Regulator	SOT23-3	TLV431CDBZx	TI
1	U102	FOD817A	IC, Optocoupler, xx-V, yy% CTR	SMT-4PDIP	FOD817xx	Fairchild
1	U103	LM5023MM	IC, AC-DC Quasi-Resonant Current Mode PWM Cont	MSOP	LM5023MM	National Ser

Notes:

1. These assemblies are ESD sensitive, ESD precautions shall be observed.
2. These assemblies must be clean and free from flux and all contaminants.
   Use of no clean flux is not acceptable.
3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.

4. Ref designators marked with an asterisk ('**') cannot be substituted.
All other components can be substituted with equivalent MFG's components.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265